



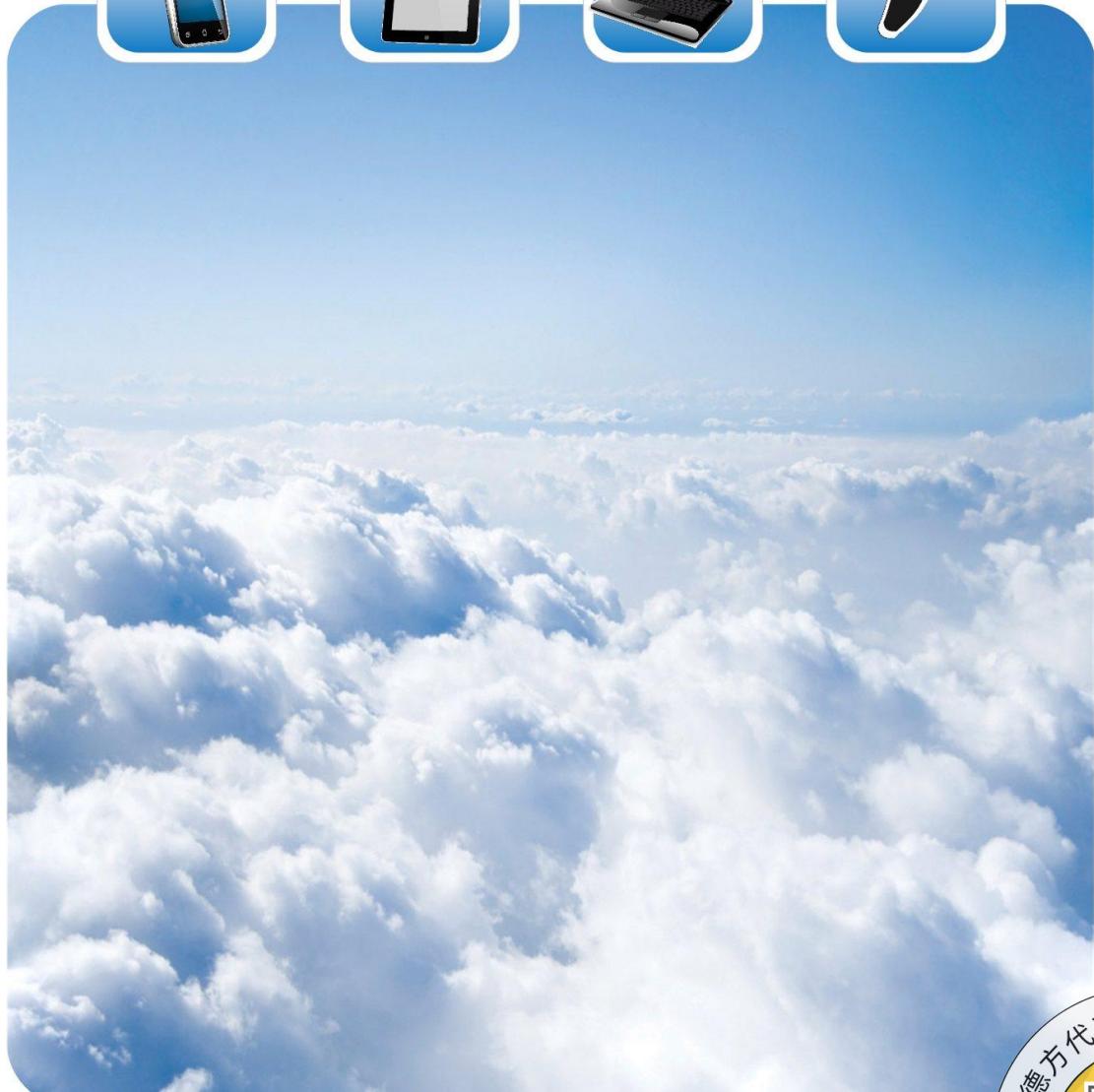
敏芯股份
MEMSensing

Data Sheet

V 1.1 / Jul. 2022

MSM421AKT002

Analog output MEMS microphone





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GENERAL DESCRIPTION

MSM421AKT002 is an omnidirectional, Top-ported, analog output MEMS microphone. It has high performance and reliability. It is with enhanced RF immunity performance .

MSM421AKT002 is available in a thin 3.76 mm × 2.95 mm × 1.10 mm metal can LGA package. It is SMT compatible with no sensitivity degradation.

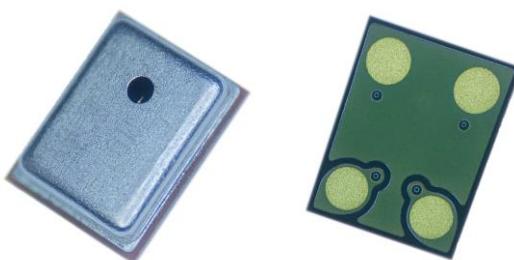
FEATURES

- ✧ Omnidirectional
- ✧ Excellent RF immunity
- ✧ Standard SMD Reflow
- ✧ Compatible with Sn/Pb and Pb-free solder processes
- ✧ RoHS/Halogen free compliant
- ✧ Sensitivity Matching within +/-1dB

APPLICATIONS

- ✧ Mobile Phone
- ✧ Laptop
- ✧ Tablet computer
- ✧ Bluetooth headset
- ✧ Earphone
- ✧ Wearable intelligent equipment

PRODUCT VIEW





ABSOLUTE MAXIMUM RATINGS

| Parameter | Maximum value | Unit |
|----------------------|---------------|--------|
| Supply Voltage | -0.3 to 4.0 | V |
| Sound Pressure Level | 140 | dB SPL |
| Storage temperature | -40 to 100 | °C |

Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.

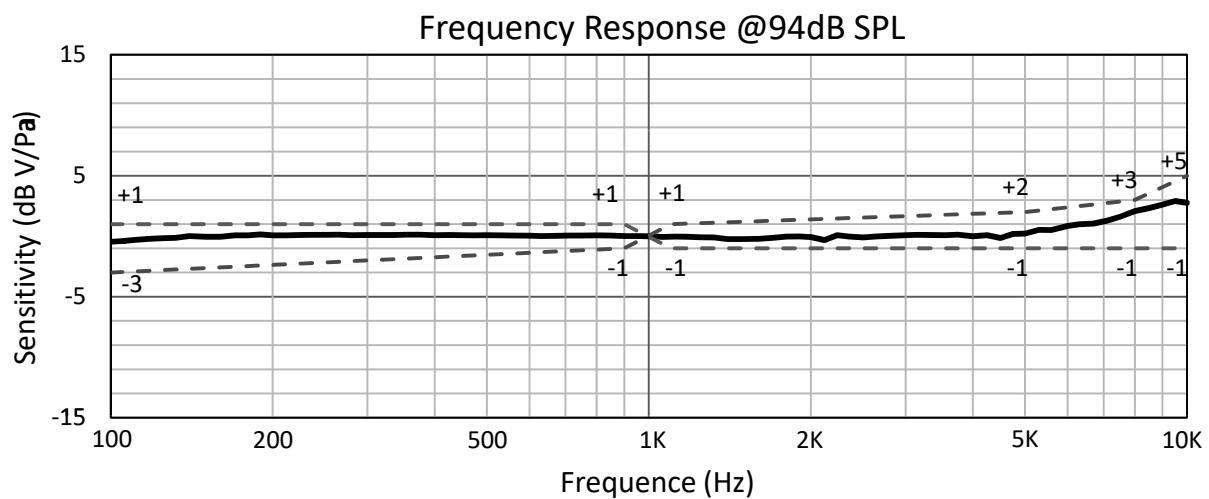
ACOUSTIC & ELECTRICAL SPECIFICATIONS

| All data taken @1.8V, 25±10°C, RH 50±20%, unless otherwise specified | | | | |
|--|---|------|------|---|
| | Limits | | unit | condition |
| | Min. | Nom. | Max. | |
| Directivity | Omni directional | | | |
| Sensitivity | -43 | -42 | -41 | dB @1kHz ref 1V/Pa |
| Operation voltage | 1.5 | - | 3.6 | V |
| Freq. range | Refer to the frequency response graphic | | | Hz Ref to sensitivity@1kHz |
| Sensitivity loss across supply voltage | No change across the voltage range | | | dB |
| Signal to noise ratio | - | 59 | - | 94dB SPL @1kHz, A-weighted |
| THD | - | 0.1 | - | % 94dB SPL @1kHz S =Nom, Rload > 2 k |
| AOP | - | 125 | - | dB SPL 10% THD @1kHz S =Nom, Rload > 2 k |
| Polarity | Increasing output voltage | | | Increasing sound pressure |
| Output impedance | - | 200 | - | Ω @1kHz |
| DC Output | 0.7 | | | V |
| PSRR | - | 70 | - | dB 200mVpp sine wave @ 1 kHz, VDD = 1.8V |
| PSR | - | -100 | - | dBV(A) 100 mVpp square wave@ 217 Hz, VDD = 1.8V, A-weighted |
| Current consumption | - | 150 | 170 | μA |



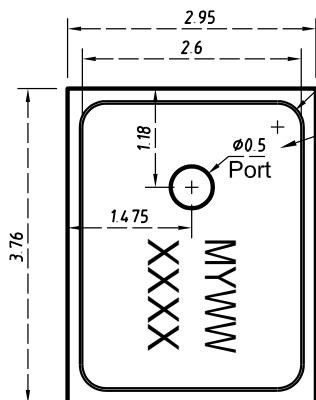
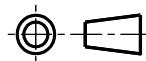


TYPICAL FREQUENCY RESPONSE

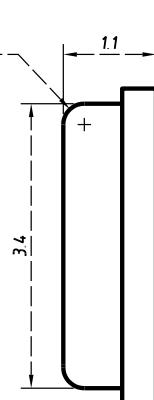




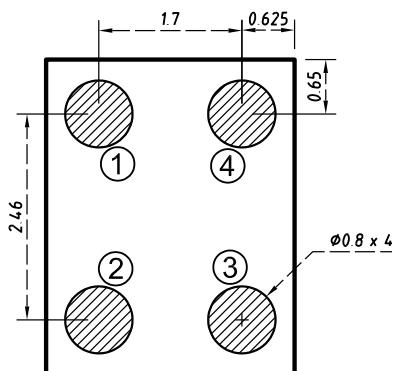
OUTLINE DIMENSIONS AND PIN DEFINITION:



TOP VIEW



SIDE VIEW



BOTTOM VIEW

PIN function description

| PIN# | Function |
|------|----------|
| 1 | VDD |
| 2 | GND |
| 3 | GND |
| 4 | OUT |

| Item | Dimension | Tolerance |
|--------------------|-----------|-----------|
| Length (L) | 3.76 | ±0.10 |
| Width (W) | 2.95 | ±0.10 |
| Height (H) | 1.10 | ±0.10 |
| Acoustic Port (AP) | Ø0.5 | ±0.05 |

Dimensions are in millimeters, tolerance is ±0.15mm unless otherwise specified.

| | | |
|--------------|------|---------------|
| MYWW XXXX | M | Memsensing |
| | Y | Year(A~Z) |
| | WW | Week |
| | XXXX | Serial Number |





RELIABILITY SPECIFICATIONS

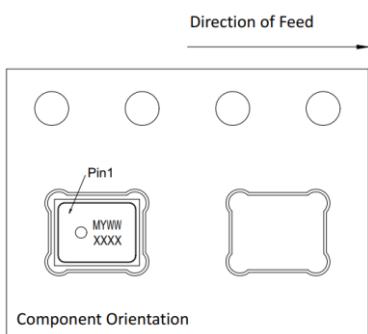
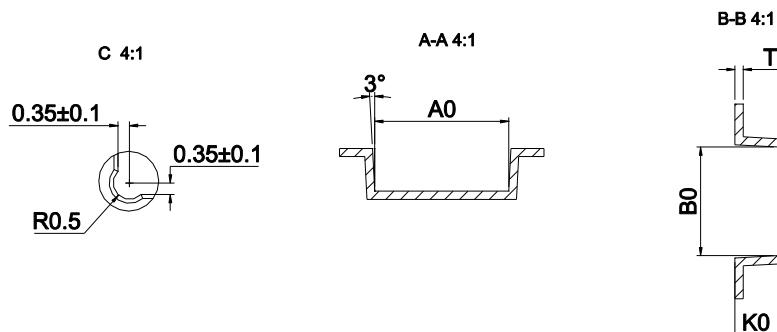
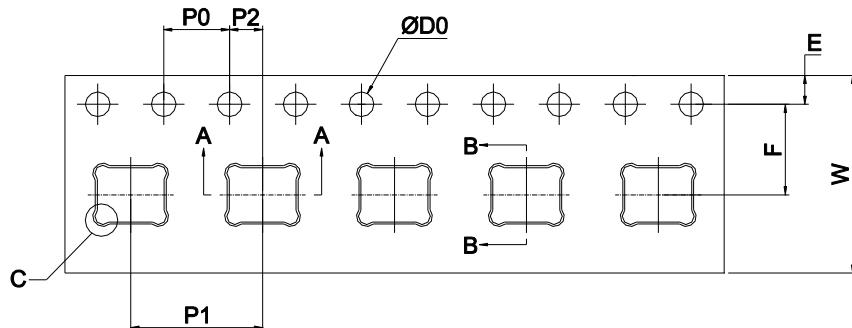
| Test | Description |
|---------------------------|--|
| Thermal Shock | 100 cycles air-to-air thermal shock from -40°C to +125°C with 15 minute soaks. (IEC68-2-4) |
| High Temperature Storage | 1,000 hours at +105°C environment. (IEC68-2-2 Test Ba) |
| Low Temperature Storage | 1,000 hours at -40°C environment. (IEC68-2-2 Test Aa) |
| Reflow | 5 reflow cycles with peak temperature of +260°C. |
| ESD-HBM | 3 discharges of ± 2 kV direct contact to I/O pins. (IEC 61000-4-2) |
| ESD-LID-GND | 3 discharges of ± 8 kV direct contact to lid while unit is grounded. (IEC 61000-4-2) |
| ESD-MM | 3 discharges of ± 200 V direct contact to I/O pins. (IEC STM5.2) |
| Vibration | 4 cycles of 20 to 2,000 Hz sinusoidal sweep with 20 G peak acceleration lasting 12 minutes in X, Y and Z directions. (Mil-Std-883E, Method 2007.2.A) |
| Mechanical Shock | 3 pulses of 10,000 G in the X, Y and Z direction. (IEC68-2-27 Test Ea) |
| High Temperature Bias | 1,000 hours at +105°C under bias (IEC68-2-2 Test Ba) |
| Low Temperature Bias | 1,000 hours at -40°C under bias (IEC68-2-2 Test Aa) |
| Temperature/Humidity Bias | 1,000 hours at +85°C/85% R.H. under bias. (JESD22-A101A-B) |
| Drop Test | To be no interference in operation after dropped to 1.0cm steel plate 18 times from 1.5 meter height |

NOTE: Sensitivity should vary within ± 3 dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $25 \pm 10^\circ\text{C}$, $50 \pm 20\%$ R.H.)





PACKAGING & MARKING DETAIL:



| ITEM | W | E | F | ØD0 | K0 |
|---------|------------|------------|-----------|------------------------------------|-----------|
| DIM(mm) | 12.00±0.30 | 1.75±0.10 | 5.50±0.10 | 1.50 ^{+0.10} ₀ | 1.30±0.10 |
| ITEM | P0 | 10P0 | P1 | A0 | B0 |
| DIM(mm) | 4.00±0.10 | 40.00±0.20 | 8.00±0.10 | 4.06±0.05 | 3.30±0.10 |
| ITEM | P2 | T | | | |
| DIM(mm) | 2.00±0.10 | 0.25±0.05 | | | |

Note:

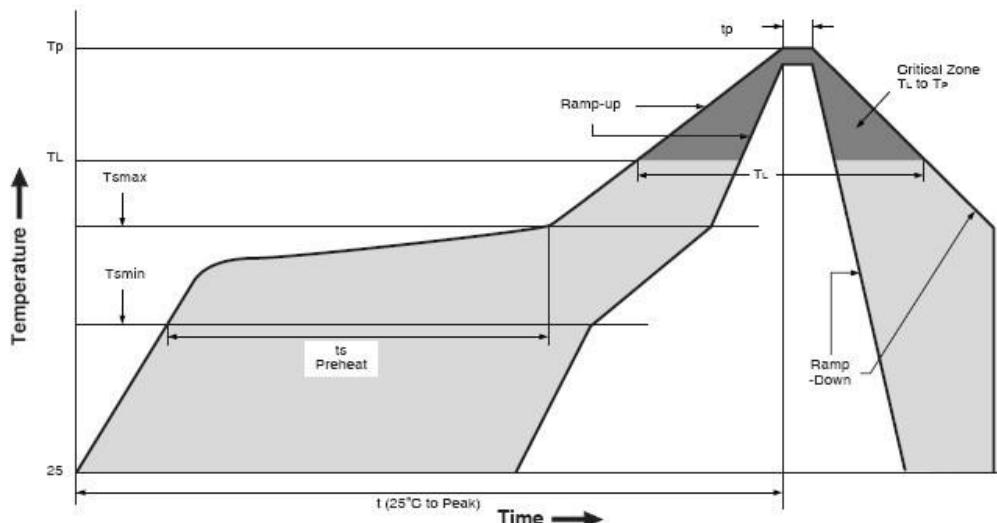
- 1) Dimensions are in mm;
- 2) Don't put the vacuum suction nozzle alignment the port hole;
- 3) Tape & Reel Per EIA-481 standard;
- 4) Label applied to external package and directly on reel;
- 5) Static voltage <100V;

| Model Number | Reel Diameter | Quantity Per Reel |
|--------------|---------------|-------------------|
| MSM421AKT002 | 13 inch | 5700 |





RECOMMEND REFLOW PROFILE:



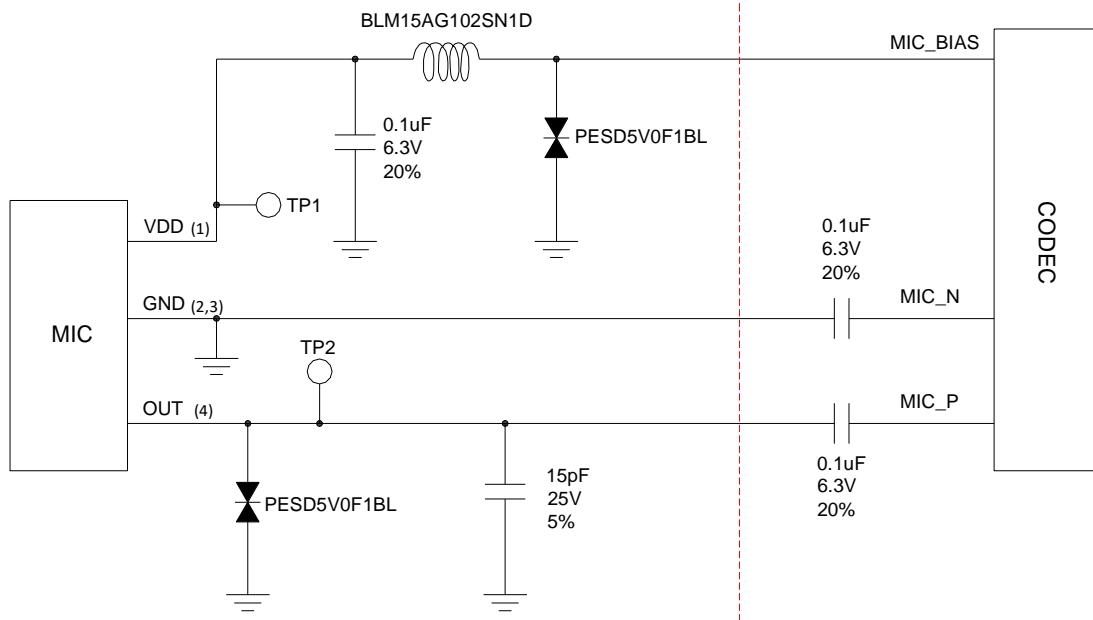
| Description | Parameter | Pb-free |
|---|-----------------------------------|-------------------|
| Average ramp-up rate | $T_{S\text{max}} \text{ to } T_p$ | 3°C/sec max |
| Preheat | | |
| Minimum temperature | $T_{S\text{MIN}}$ | 150 °C |
| Maximum temperature | $T_{S\text{MAX}}$ | 200 °C |
| Time($T_{S\text{MIN}}$ to $T_{S\text{MAX}}$) | t_s | 60 sec to 180 sec |
| Ramp-up rate | $T_{S\text{MAX}} \text{ to } T_L$ | 1.5 ~ 2°C/sec |
| Time maintained above liquidus temperature | t_L | 60 sec to 150 sec |
| Liquidus temperature | T_L | 217 °C |
| Peak temperature | T_p | 260 °C |
| Time within 5°C of actual peak temperature | t_p | 20 sec to 40 sec |
| Ramp-down rate | $T_p \text{ to } T_{S\text{max}}$ | 6 °C/sec max |
| Time 25 °C ($t_{25^\circ\text{C}}$) to peak temperature | t | 8 minutes max |

NOTE: When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.



RECOMMENDED INTERFACE CIRCUIT:

- Recommended Application Example (differential amplification circuit)



NOTE: It is recommended that the components on the left side of red line be placed close to MIC, and components on the right side of red line be placed close to codec.





ADDITIONAL NOTES

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
 - Do not board wash or clean after the reflow process.
 - Do not brush board with or without solvents after the reflow process.
 - Do not directly expose to ultrasonic processing, welding, or cleaning.
 - Do not insert any object in port hole of device at any time.
 - Do not apply air pressure into the port hole.
 - Do not pull a vacuum over port hole of the microphone.
 - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

STORAGE AND TRANSPORTATION

- (A) Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
Recommend floor life (out of bag) at factory no more than 4 weeks.
- (B) The MEMS MIC with normal pack can be transported by ordinary conveyances.
Please protect products against moist, shock, sunburn and pressure during transportation.

MATERIALS STATEMENT

Meet the requirements of MEMSensing standard on hazard substances control (including RoHS2.0+REACH+Halogen-Free, etc.), with "HSF" identification on label.





REVISION HISTORY:

| Revision | Subjects (major changes since last revision) | Date |
|----------|--|------------|
| 1.0 | Initial Release | 2022-05-19 |
| 1.1 | Update Acoustic Specifications | 2022-07-13 |

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